

# Progress and Opportunities of the Transient Liquid Assisted Growth (TLAG) method

Teresa Puig<sup>1</sup>

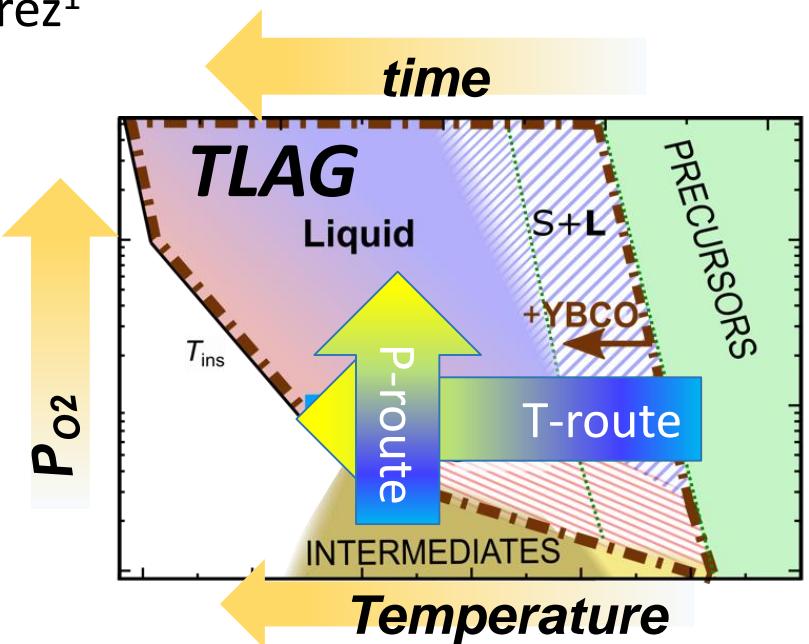
X. Obradors<sup>1</sup>, R. Vlad<sup>1</sup>, E. Pach<sup>1,4</sup>, C. Pop<sup>1</sup>, K. Gupta<sup>1</sup>, C. Torres<sup>1</sup>, O. Mola<sup>1</sup>, A. Kethamkuzhi<sup>1</sup>, E. Ghiara<sup>1</sup>, V. Bertini<sup>1</sup>, M. Voulhoux<sup>1</sup>, D. Sanchez<sup>2</sup>, S. Rasi<sup>1</sup>, L. Salterilli<sup>1</sup>, D. Garcia<sup>1,3</sup>, S. Ricart<sup>1</sup>, M. Tristany<sup>1</sup>, R. Yanez<sup>3</sup>, J. Farjas<sup>2</sup>, E. Solano<sup>4</sup>, L. Simonelli<sup>4</sup>, J. Gutierrez<sup>1</sup>

<sup>1</sup> Institut de Ciència de Materials de Barcelona, ICMAB-CSIC, Spain

<sup>2</sup> GRMT, Department of Physics, University of Girona, Spain

<sup>3</sup> Departament de Química, Universitat Autònoma Barcelona, Spain

<sup>4</sup> ALBA Synchrotron, Barcelona, Spain



# AIM: Design a robust, high throughput and flexible growth method for the manufacturing of CC at competitive cost/performance ratio

## Opportunities of TLAG

- High growth rates > 1000 nm/s
- Compatible with low-cost chemical solution deposition (CSD) and others (i.e Low Temperature PLD deposition, LTPLD)
- Wide processing window
- Compatible with different Rare Earth (RE) and nanocomposite growth
- Well-suited for large area fabrication
- Easily scalable manufacturing equipment

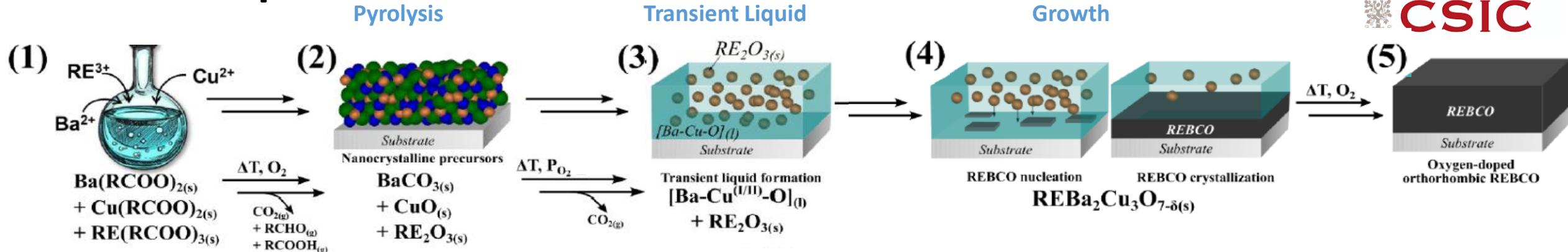
## Need of R&D in advanced CC materials

- Generate new ideas and understanding
- Develop breakthroughs that enable high-volume CC production at lower cost/performance
- Fast screening methodologies and AI approaches to guide predictions
- Contribute to making CC production a sustainable and transformative technology

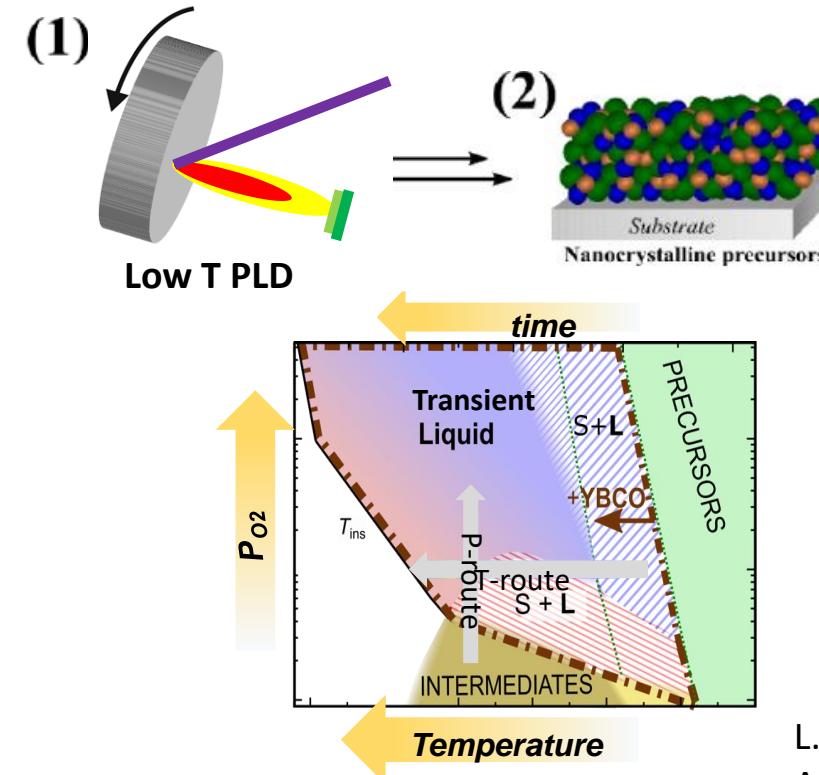
## Outline

- Progress in process understanding and processing windows
- Growth rates
- High Throughput Experimentation approach
- Vortex pinning and overdoping
- Towards large area Coated Conductors

# ① TLAG-CSD process



# TLAG-PLD process

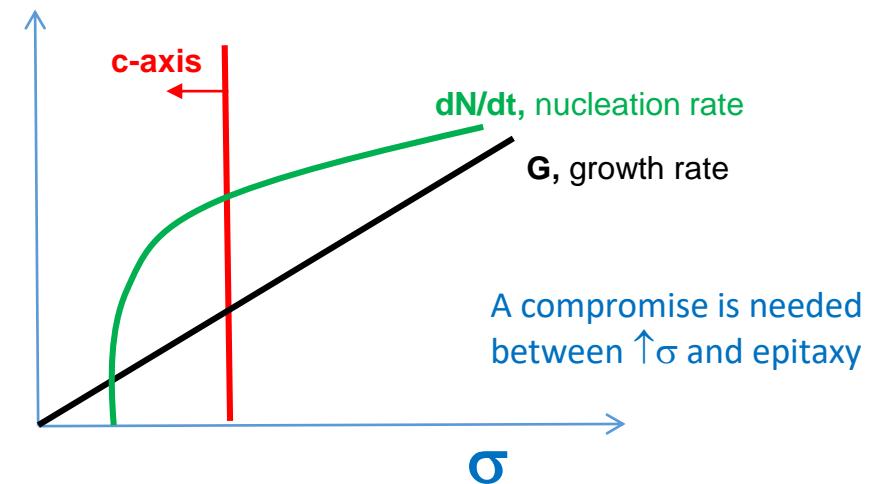


Kinetically governed by RE liquid supersaturation  $\sigma = (\text{C}_\delta - \text{C}_e) / \text{C}_e$

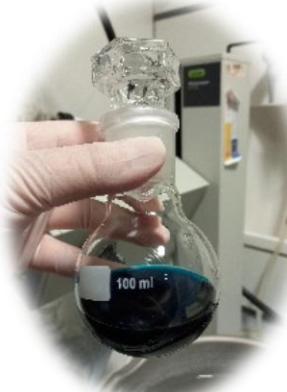
$\text{C}_e$ : thermody. param. ( $T, P_{\text{O}_2}$ , Ba/Cu liq. composition, RE ion)  
 $\text{C}_\delta$ : kinetic param. (heating ramp, pressure ramp, ...)

if  $1/T, P_{\text{O}_2}$ , Ba/Cu or  $r_{\text{RE}} \uparrow \rightarrow \sigma \uparrow$

Fast advanced tools have  
been developed to  
understand the process

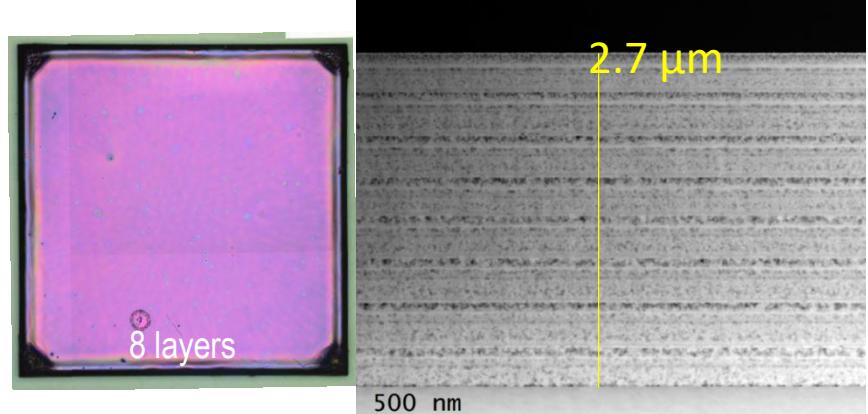
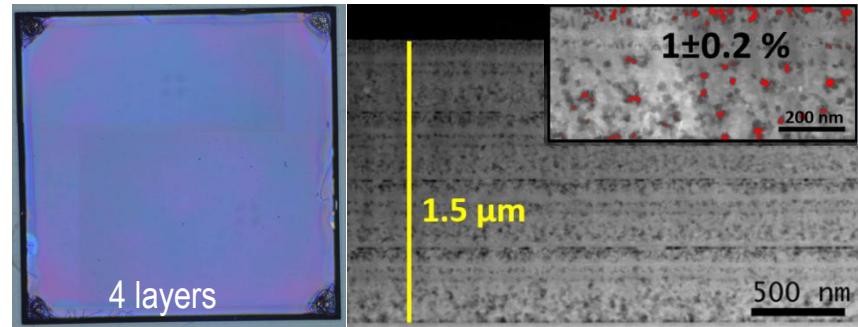


# Inks, pyrolysis and multidepositions in TLAG-CSD



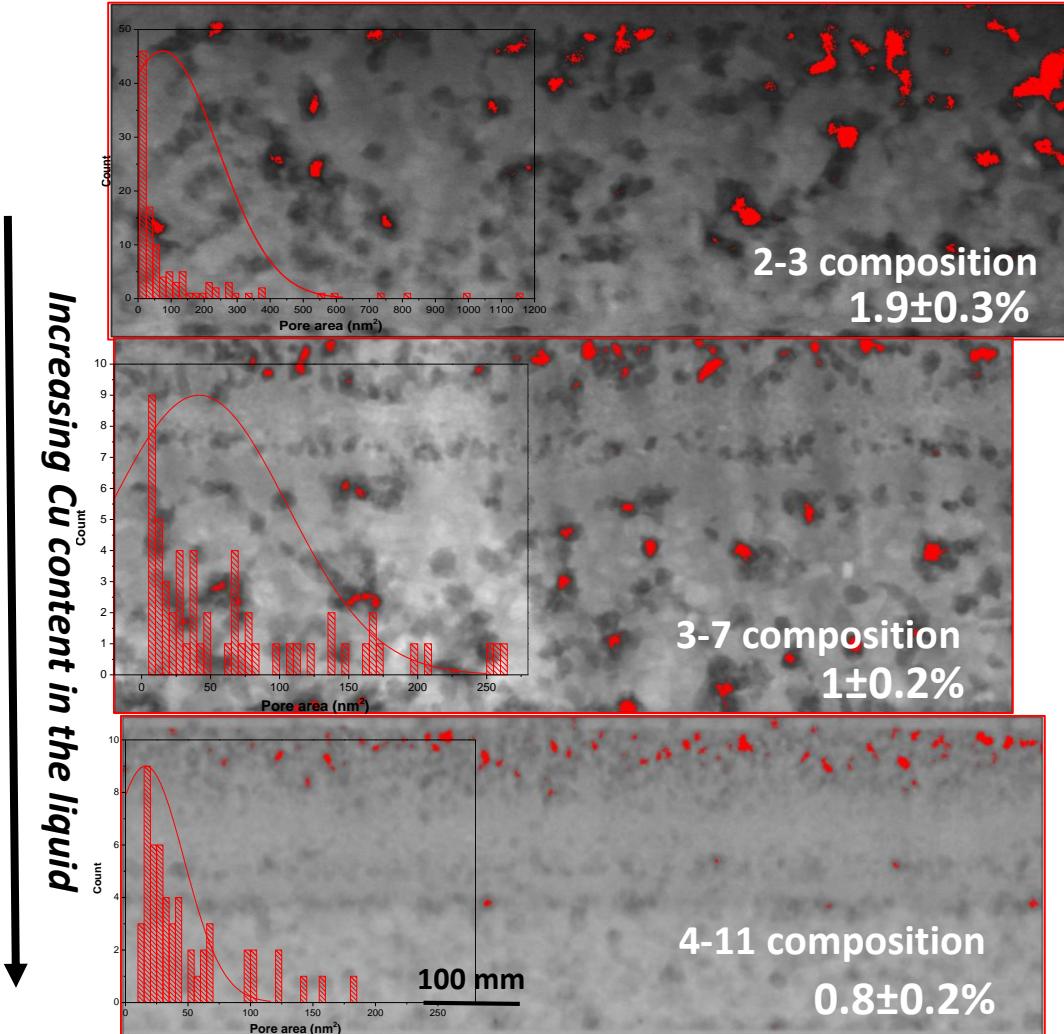
Multifunctional ink  
Patent EP22382741

Adapted to multideposition with  
no loss in homogeneity



Also demonstrates for  
REBCO inks with RE= Y,  
Er, Gd, Sm, Yb

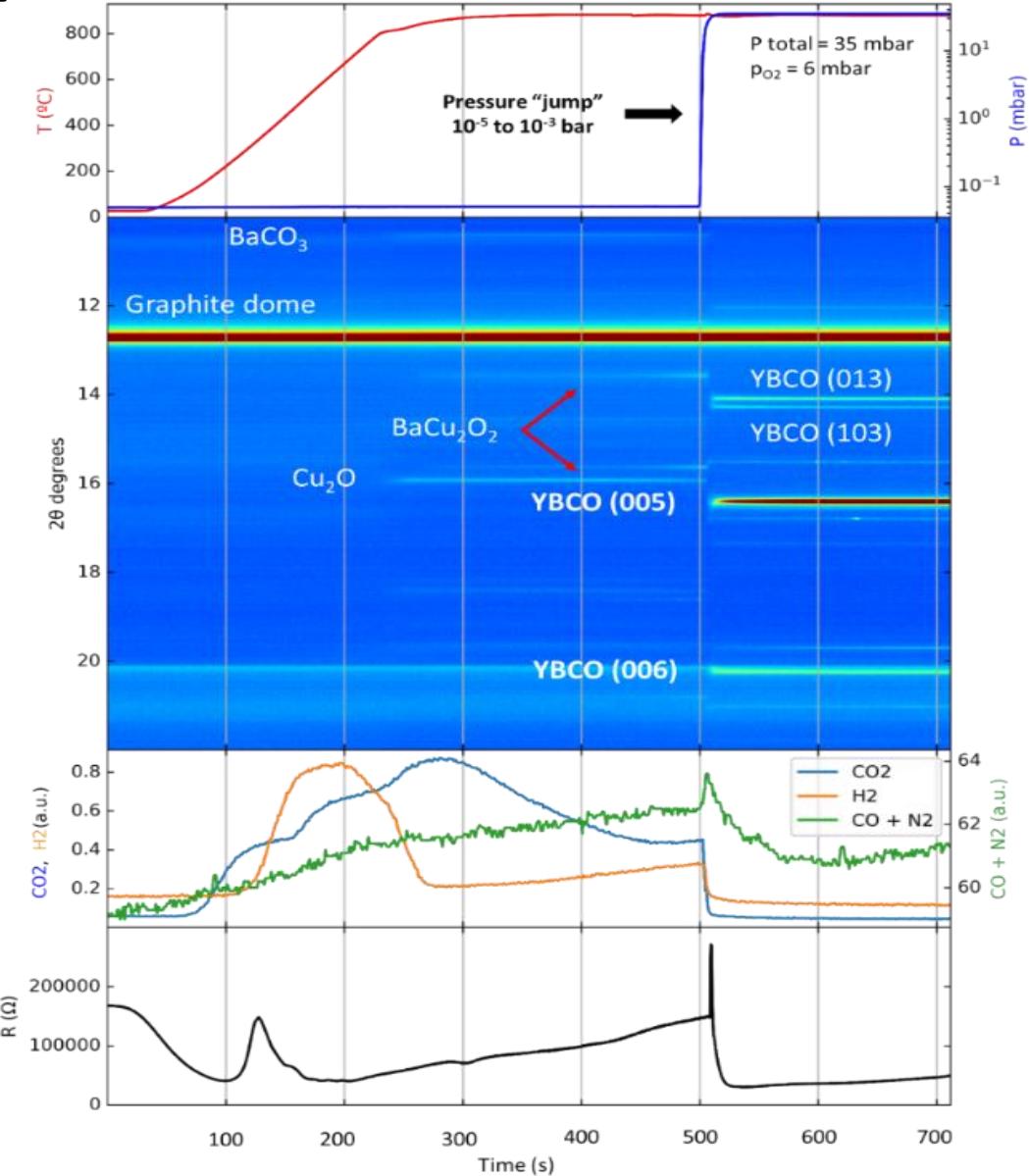
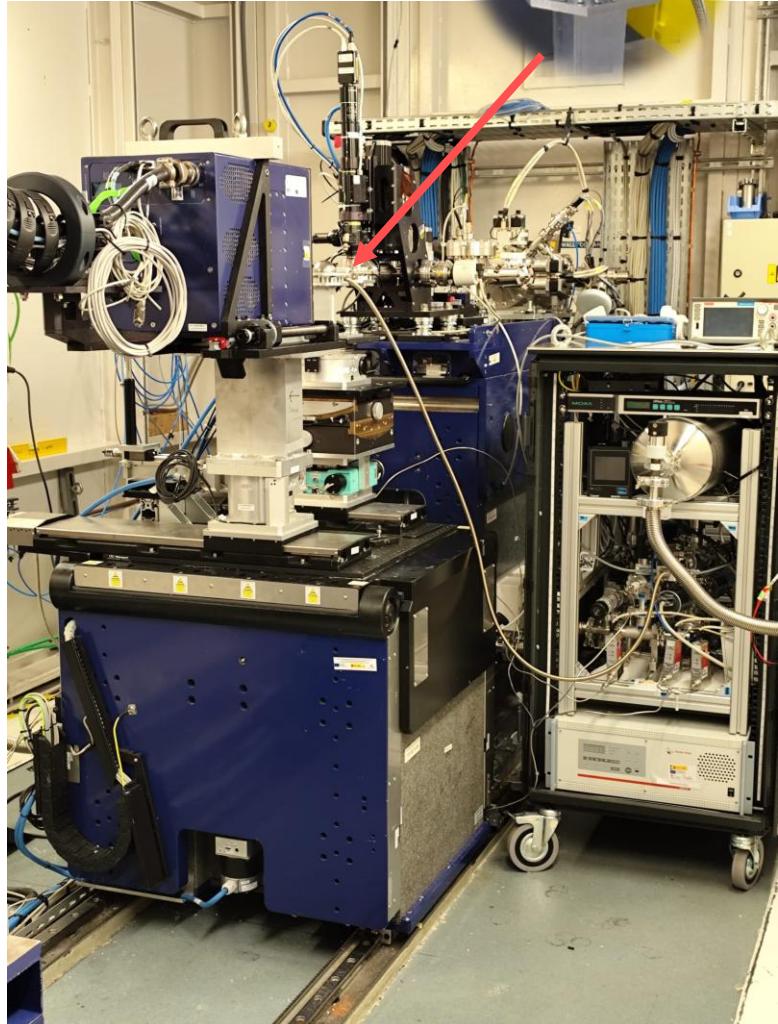
The increase in Cu content facilitates the decrease of supersaturation



## ② Understanding TLAG growth mechanisms through in-situ 2D X-Ray Diffraction (XRD)



NCD-SWEET beamline



ETJL Joint laboratory

IIF FARADAY  
JAPAN FACTORYTLAG-LTPLD  
experiments  
March 2025

Experiment conditions

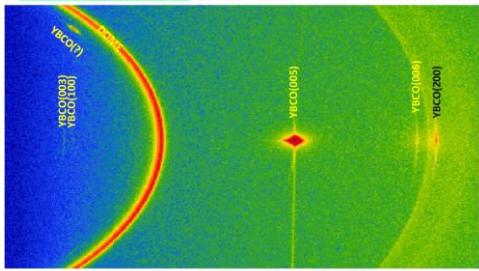
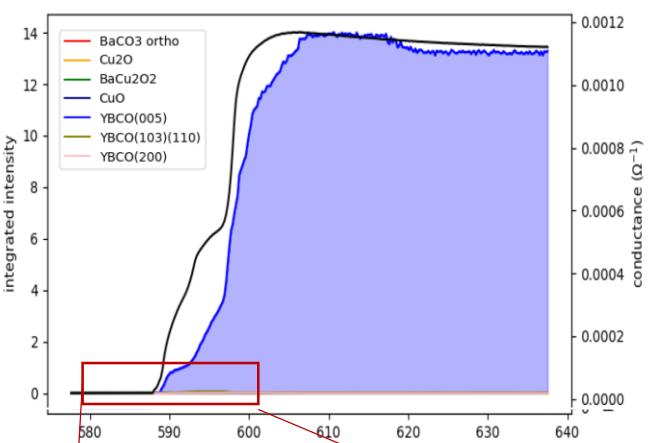
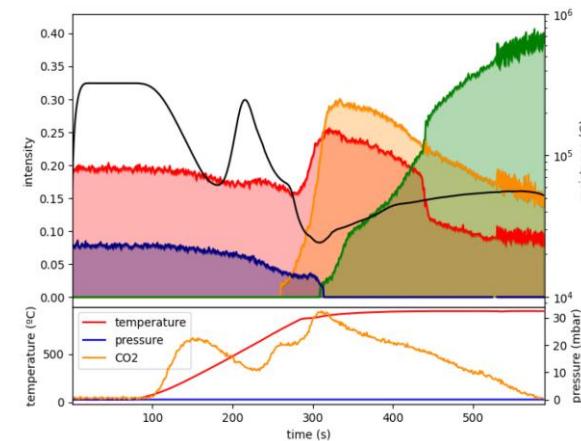
ALBA

Synchrotron XRD

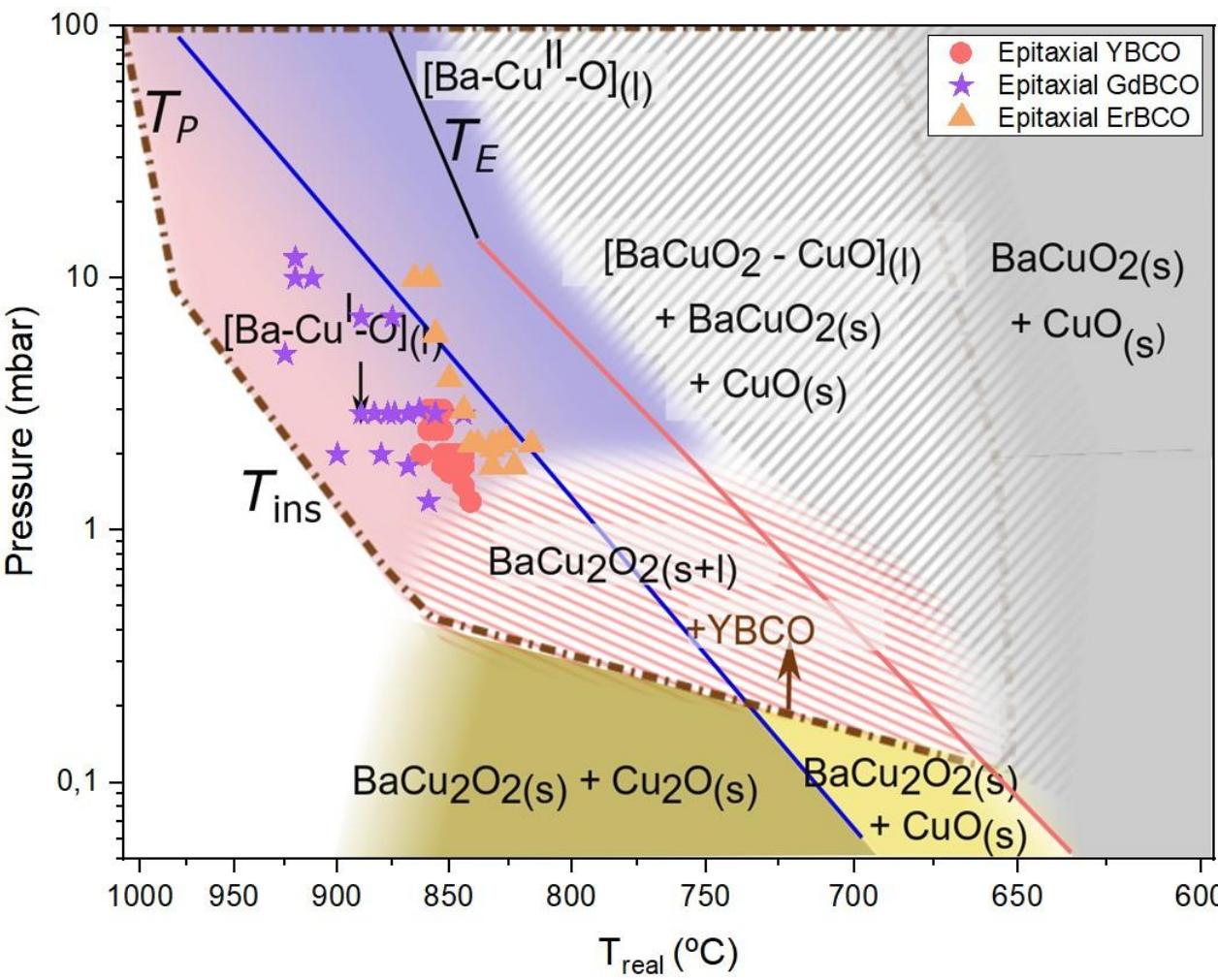
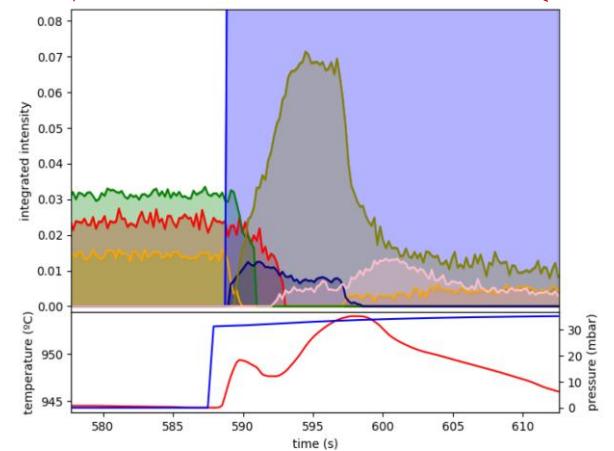
Mass spectroscopy

Resistivity

# TLAG kinetic phase diagram from evolution of phases



Epitaxial growth

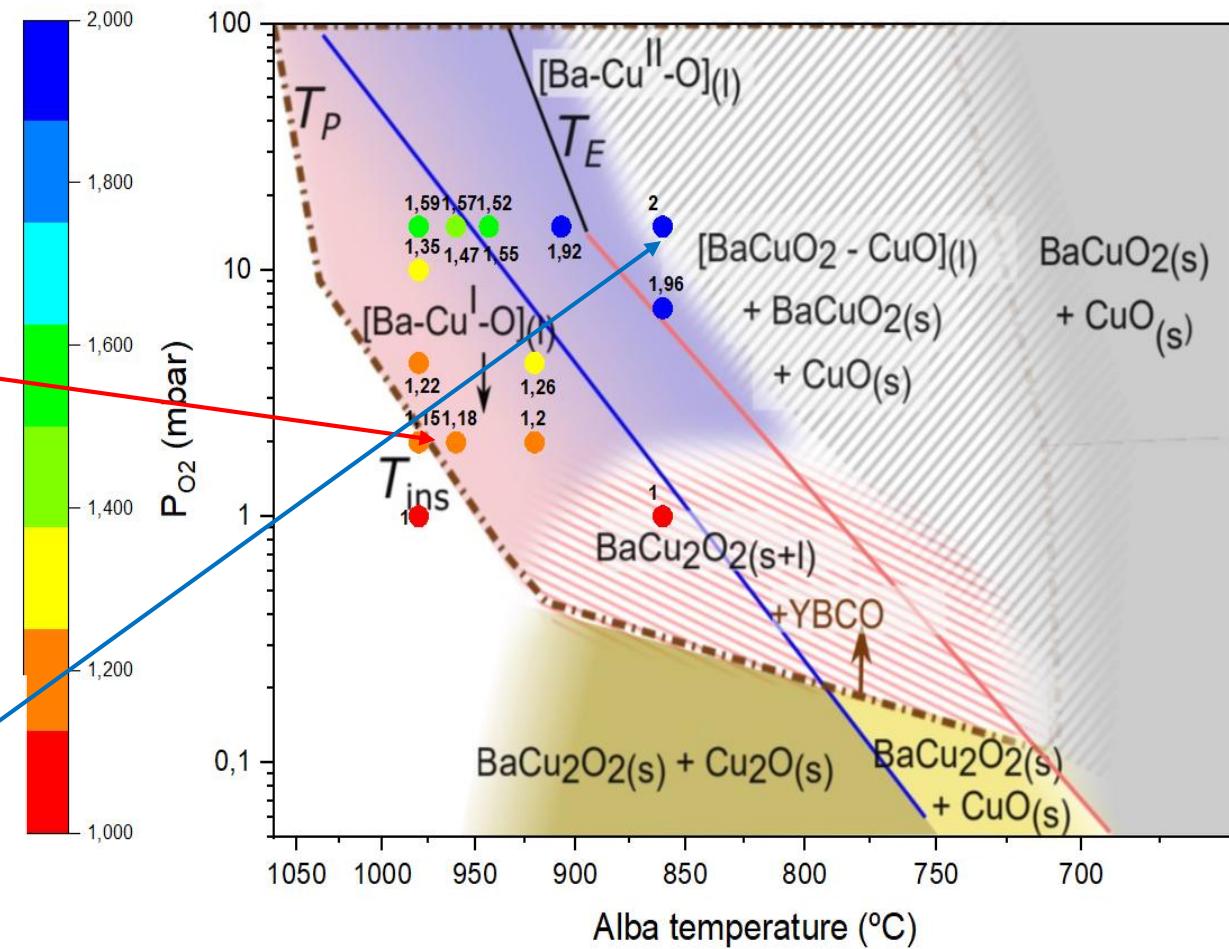
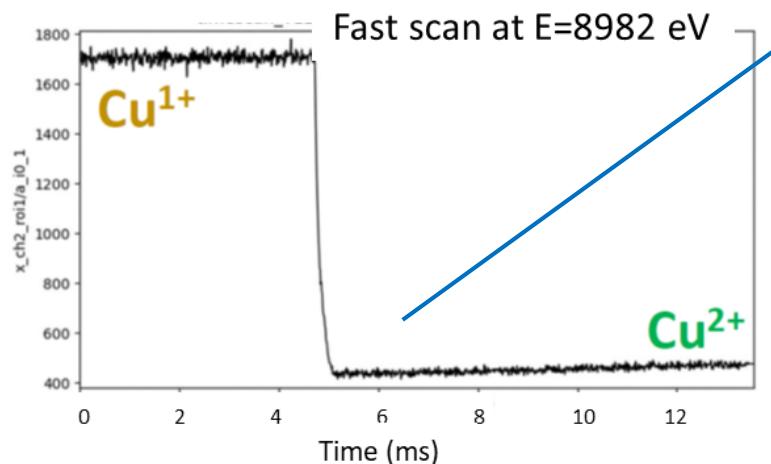
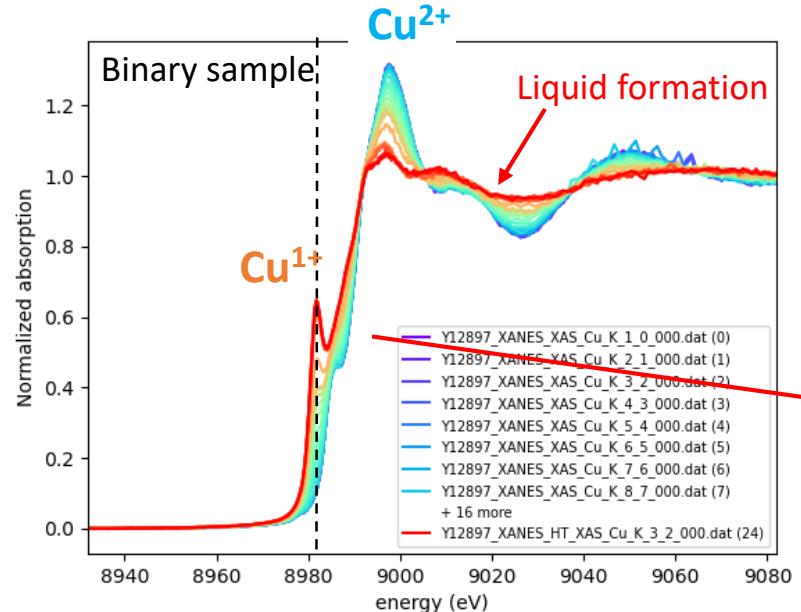
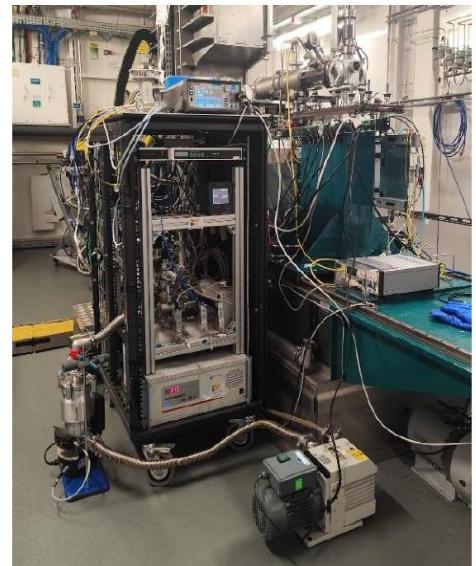


Wide processing window further controlled by RE ion

# Understanding TLAG growth mechanisms through in-situ X-Ray Absorption Spectroscopy (XAS)



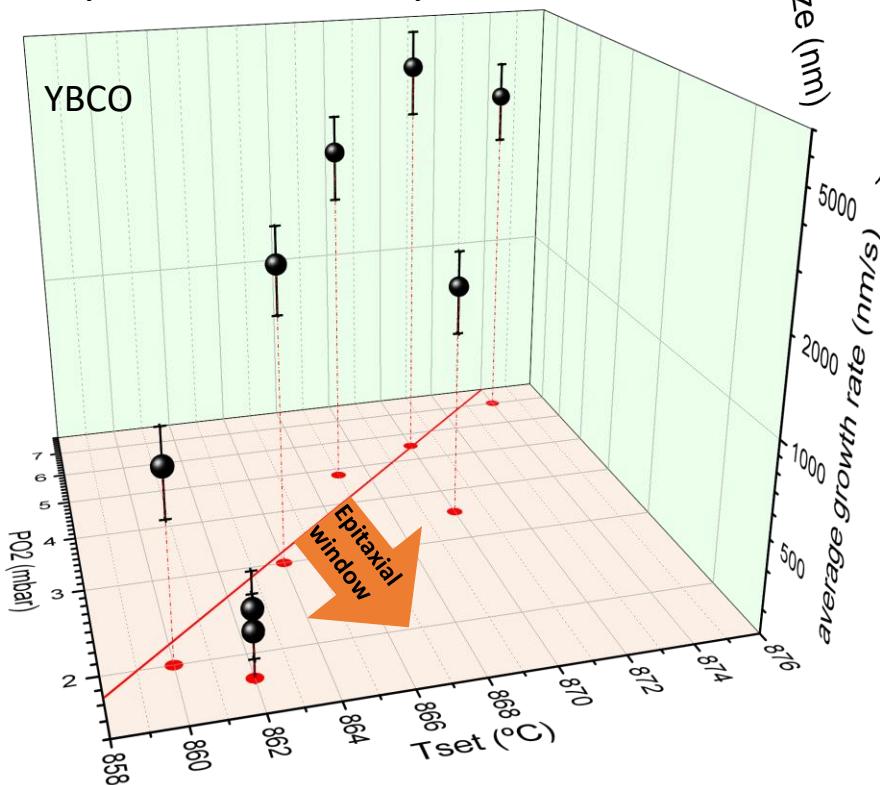
**CLAES beamline**



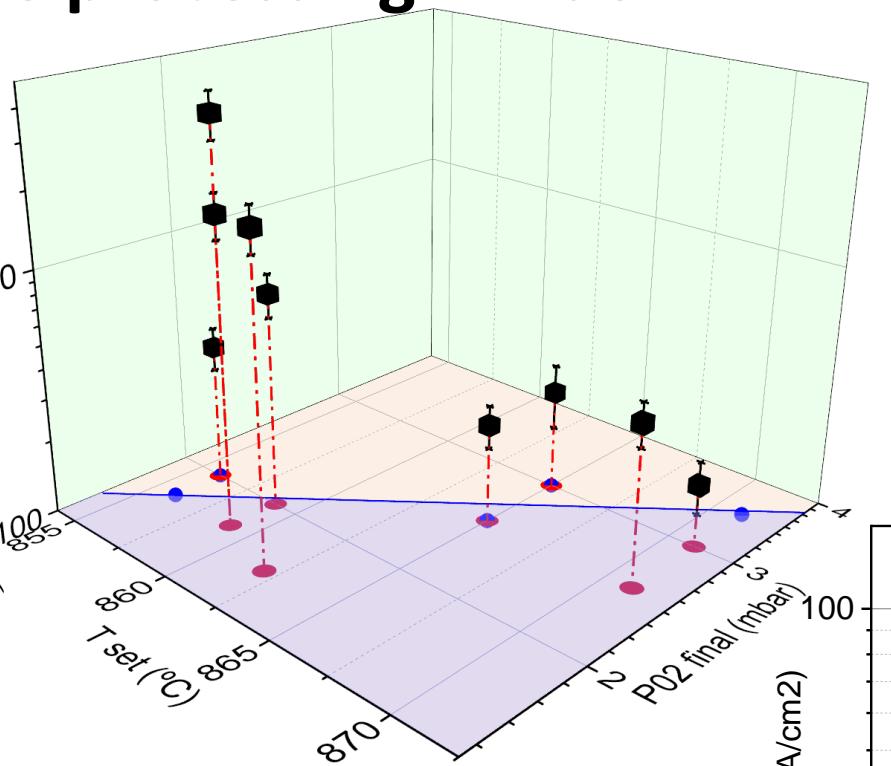
**Identification of liquid characteristics in the processing window**

### ③ TLAG growth rates in the processing window

By in-situ resistivity

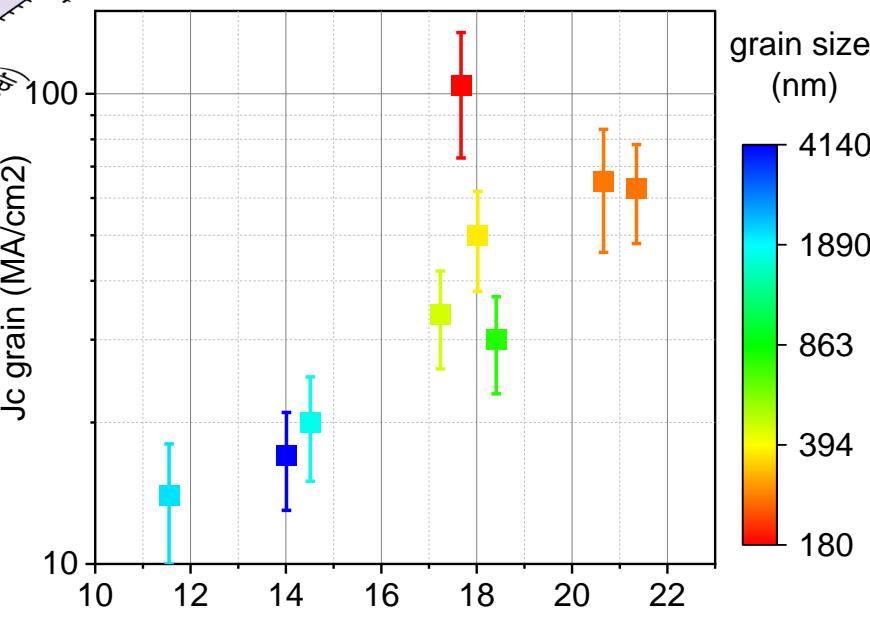


Growth rate, G,  $\uparrow$  if  $P_{O_2}$  (and T)  $\uparrow$

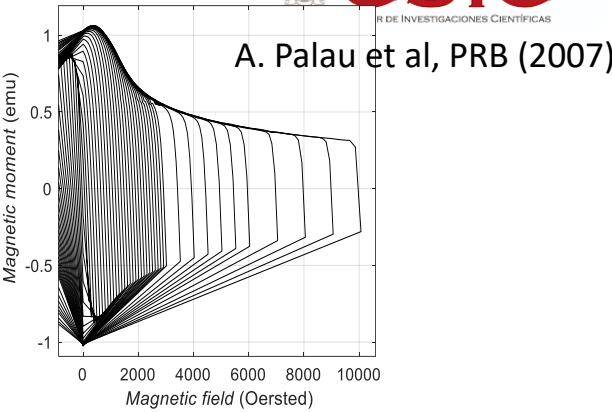


Grain size, a,  $\downarrow$  if  $P_{O_2}$  (and T)  $\uparrow$   
(in agreement with  $\uparrow$  nucleation density and  $\uparrow$  supersaturation)

Going to high G is  
beneficial also for  $J_c$



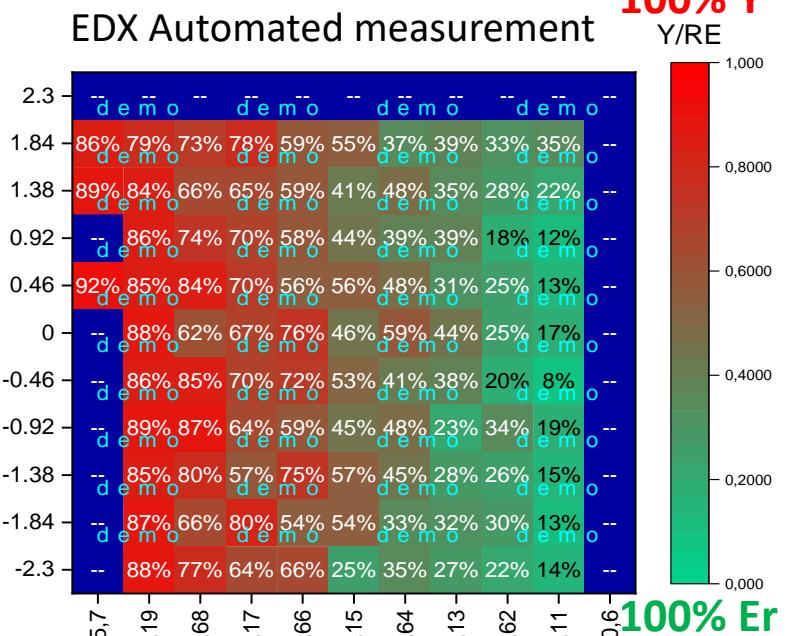
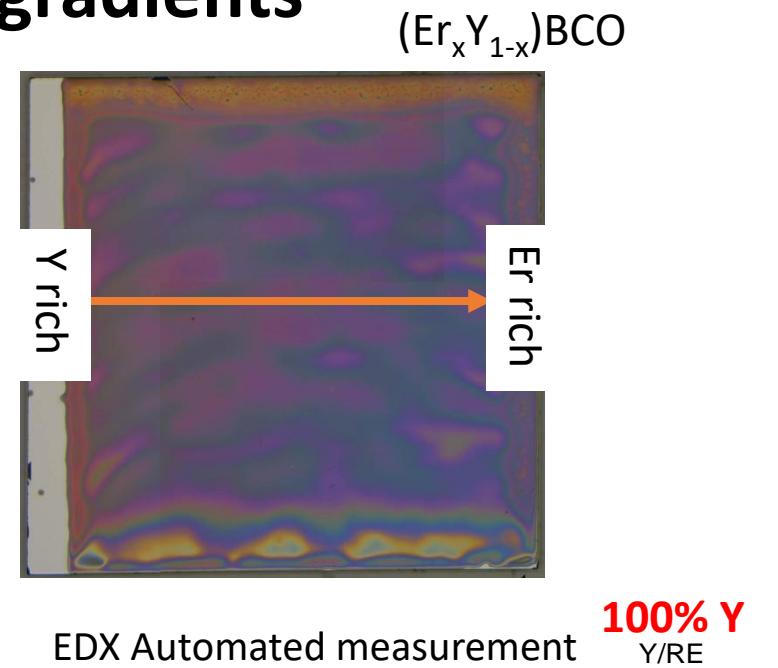
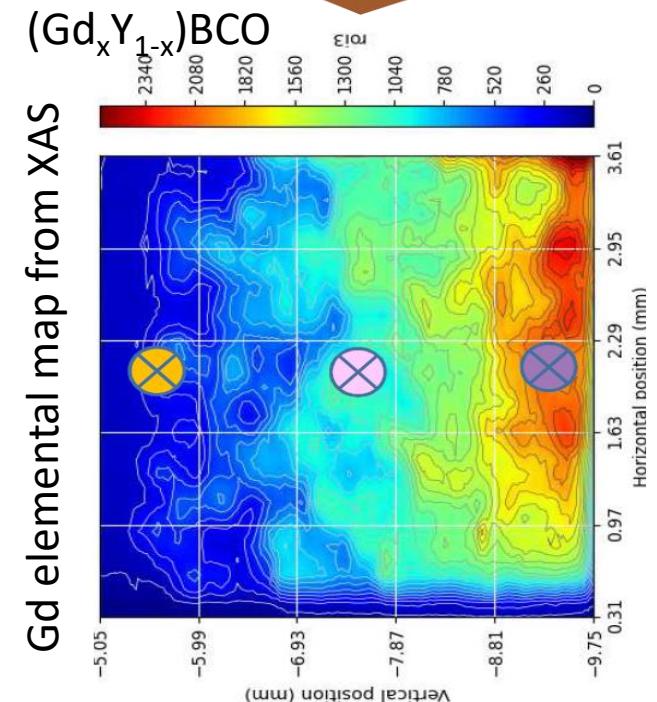
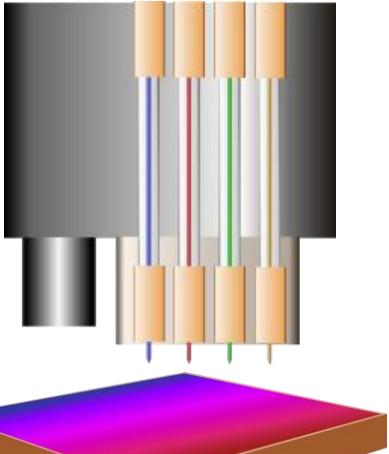
$J_c \uparrow$  if grain size, a,  $\downarrow$   
(in agreement with other CSD methods)



④

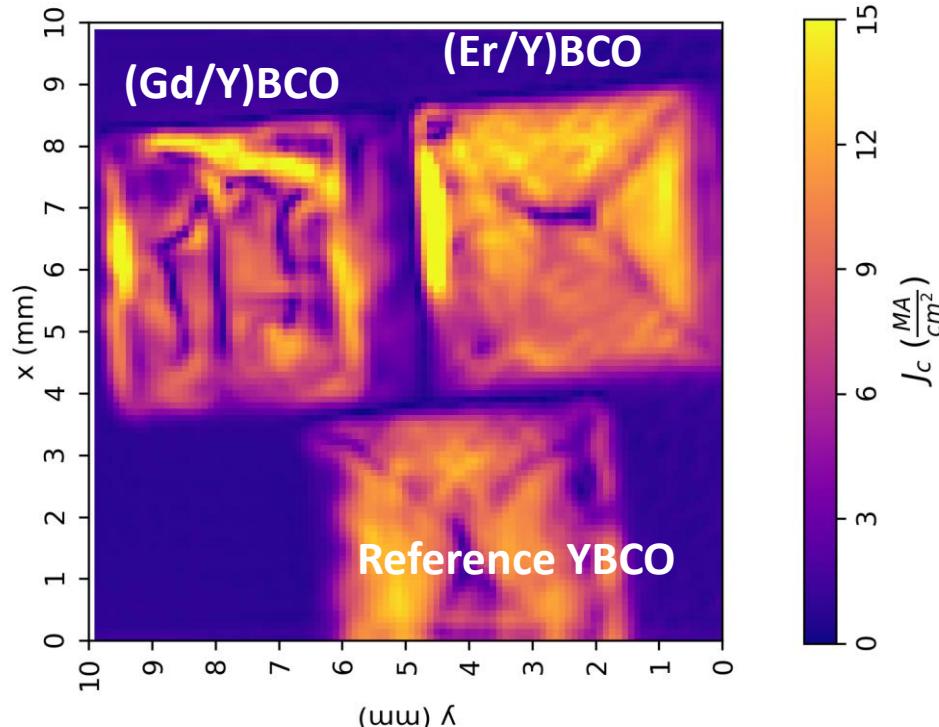
# High Throughput Experimentation using Combinatorial RE Compositional gradients

Via inkjet printing



Collab. Z. Wu, T. Kiss

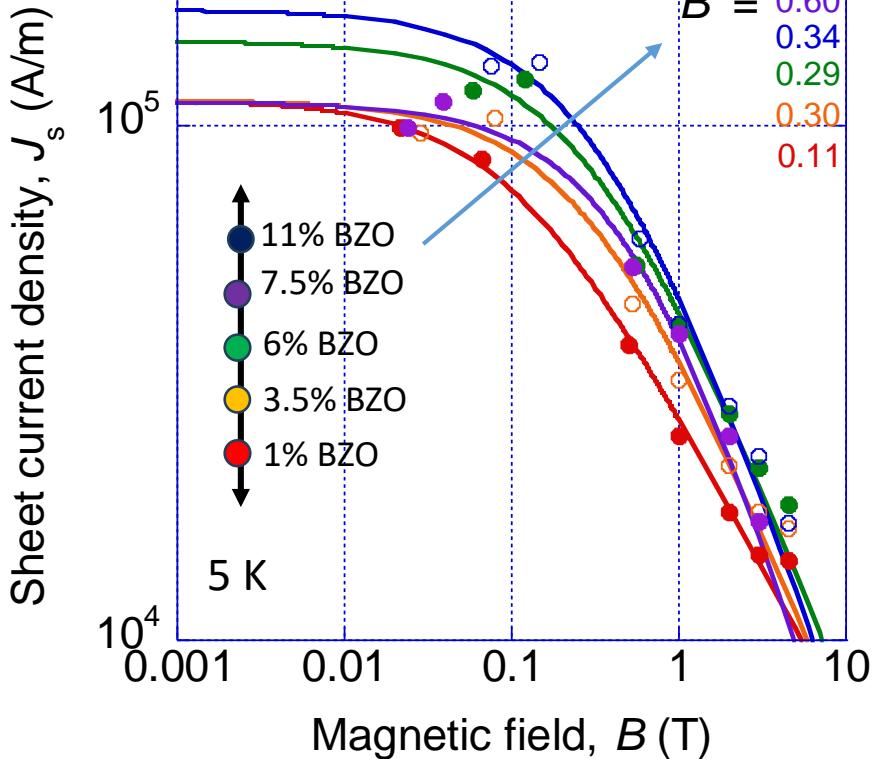
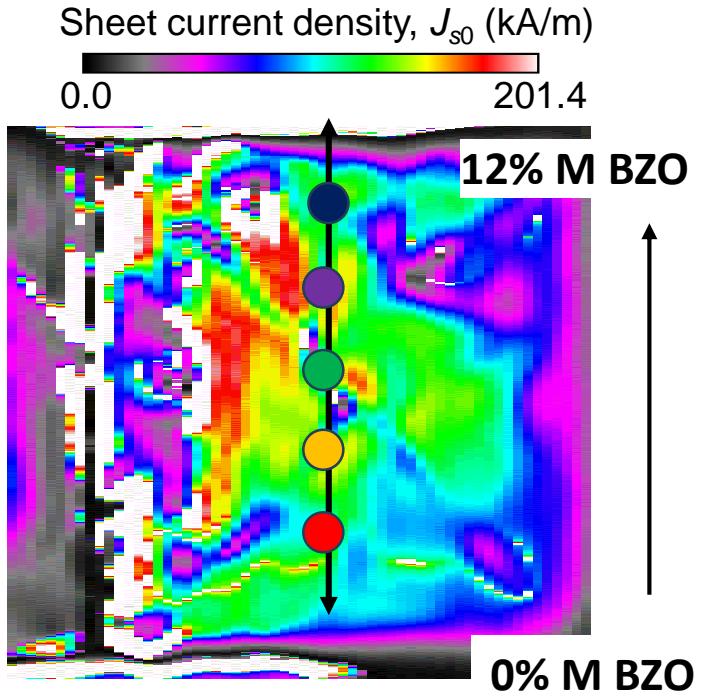
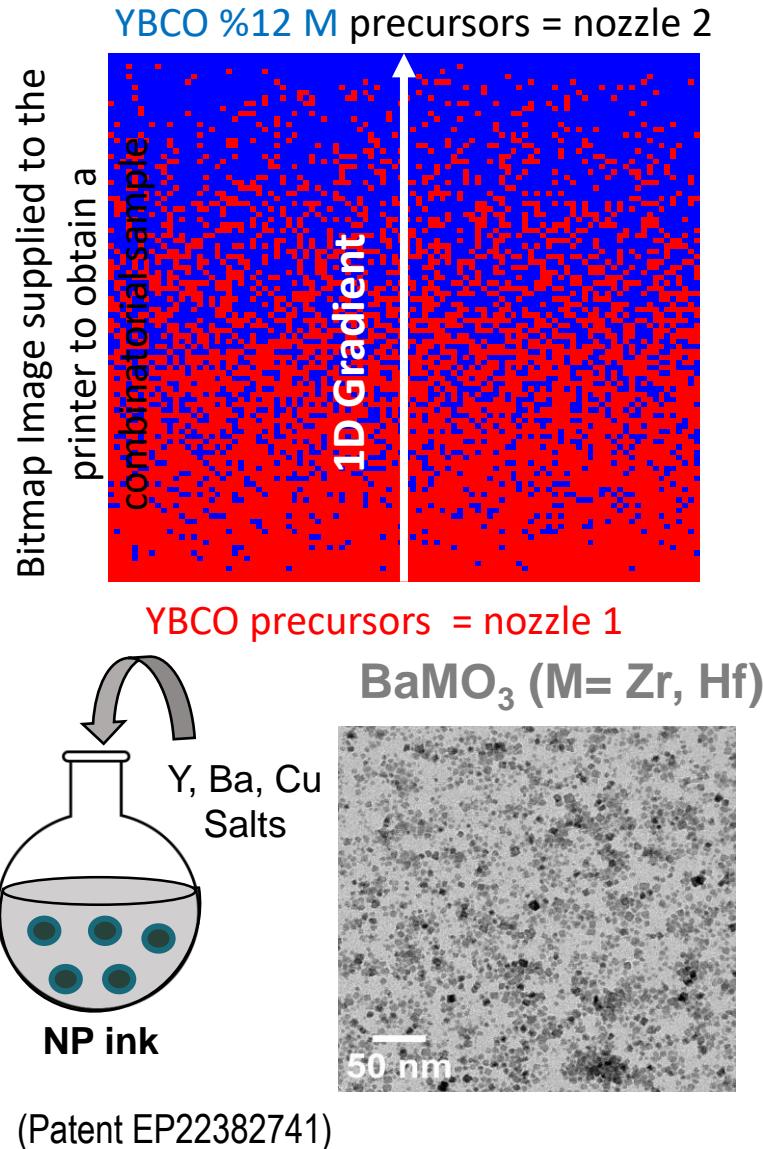
Scanning Hall Probe Microscopy



Towards Machine Learning strategies for  $J_c$  prediction

T. Puig -CCA2025

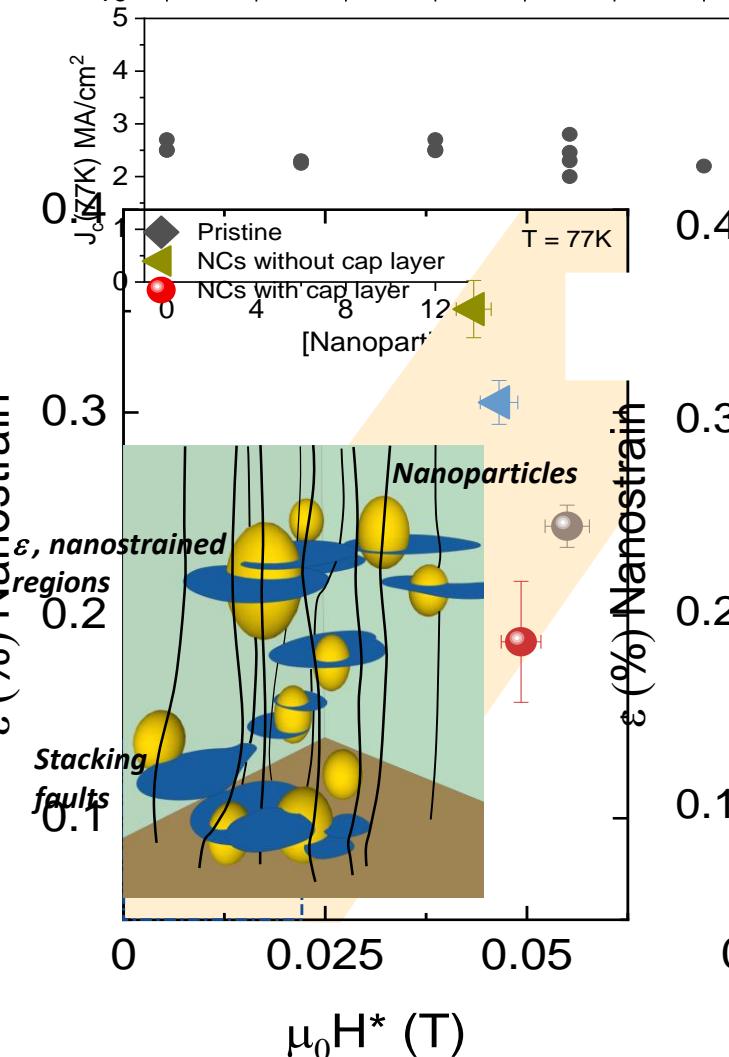
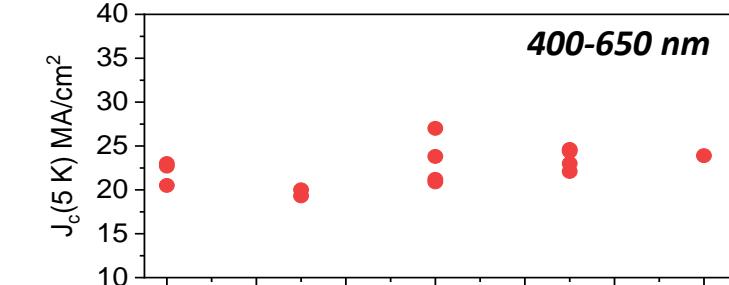
# High Throughput Experimentation using Combinatorial Compositional gradients: Nanocomposites (work in progress)



Open opportunities towards gradients  
with different nanoparticles  
composition and size

$$J_s(B, x, y) = J_{s0}(x, y) * \left(1 + \frac{B}{B^*(x, y)}\right)^a$$

# ⑤ Vortex Physics in TLAG Nanocomposites



Tuning of vortex pinning by nanostrain and nanoparticles depend on process parameters (i.e. supersaturation, growth rate)

STEM-HAADF

nanocomposite

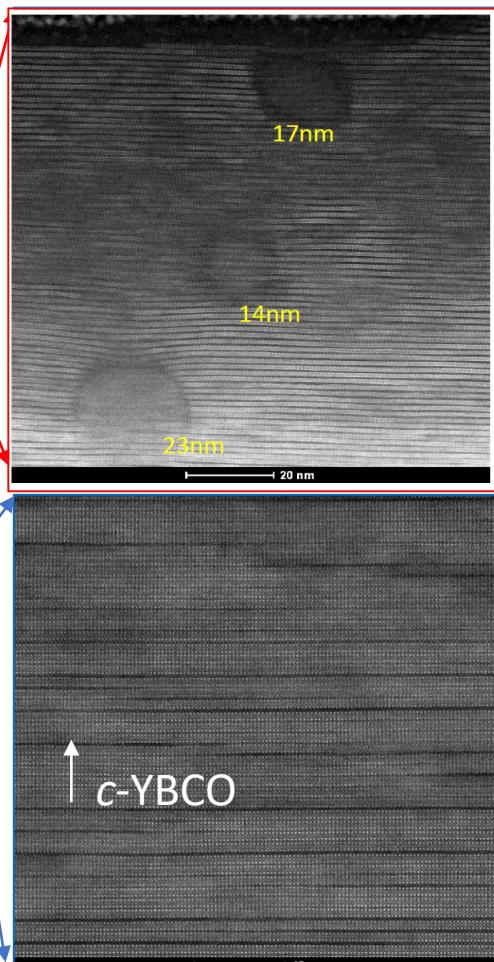
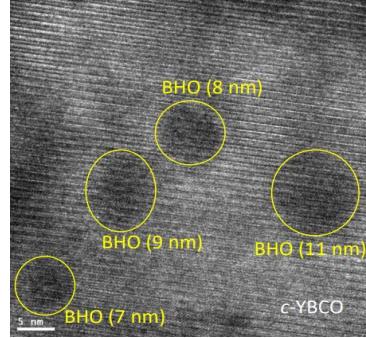
Pristine

c-YBCO

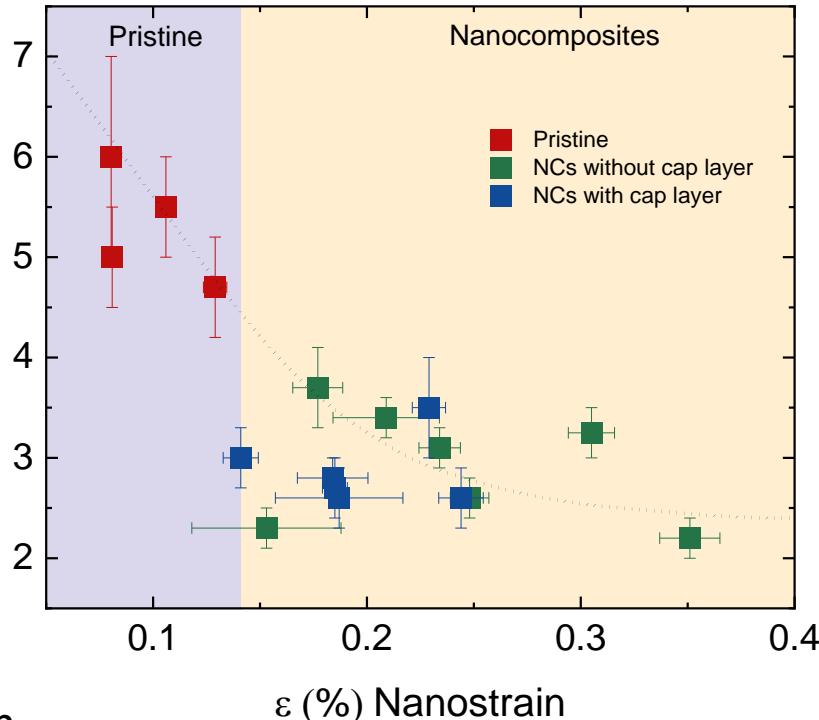
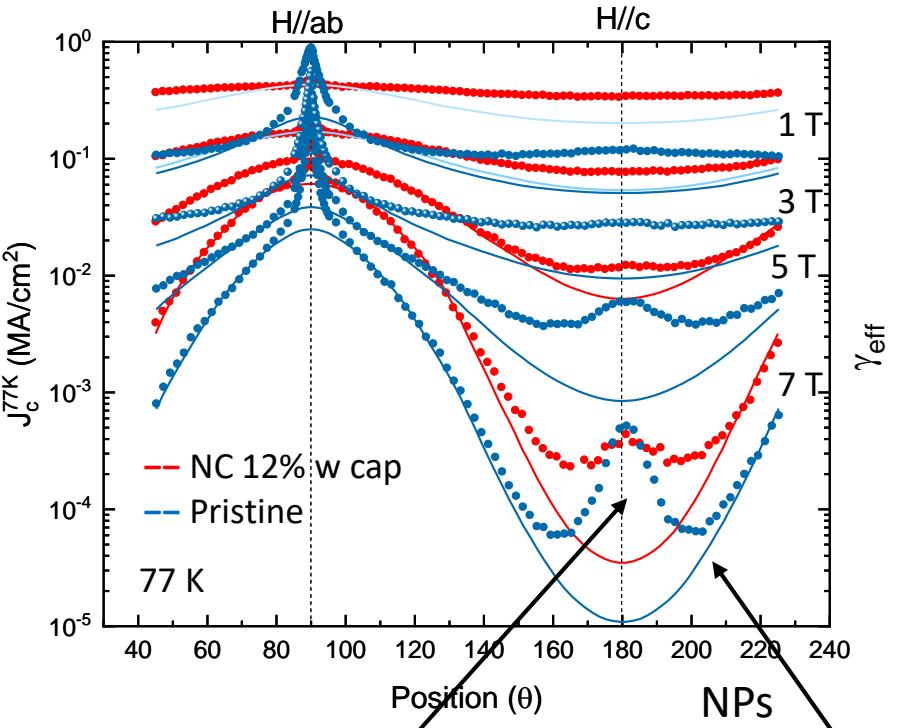
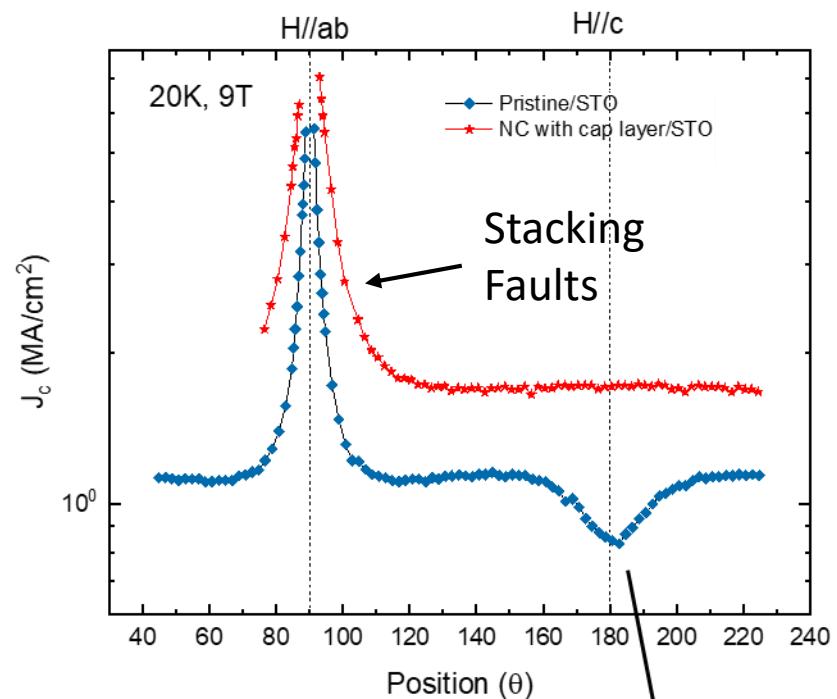
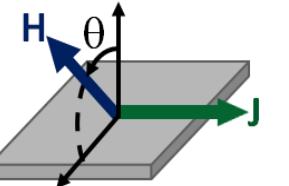
c-YBCO

50 nm

$\mu_0 H^* (\text{T})$



# Vortex Pinning anisotropy in TLAG films



Blatter scaling approach

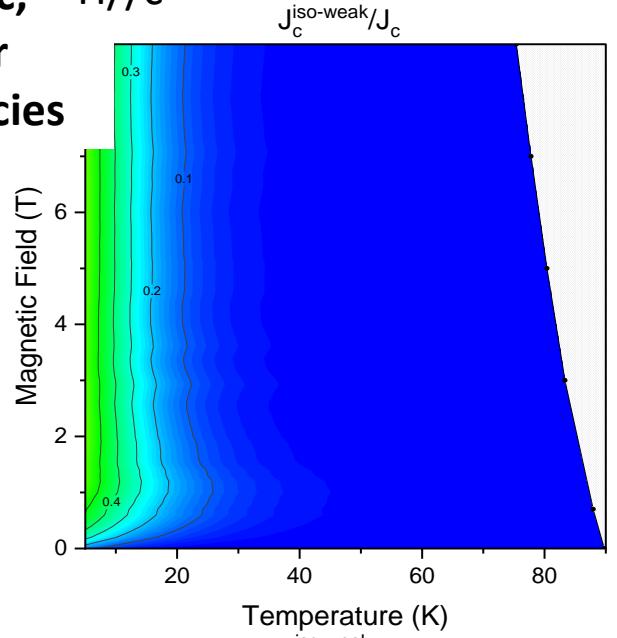
$$J_c^{iso} = J_c^{H//c} \left( \sin^2 \theta / \gamma_{eff}^2 + \cos^2 \theta \right)$$

Nanocomposites decrease vortex dissipation and induce less anisotropy  
 Vortex behaviour depends on T, H,  $\theta$  and process parameters

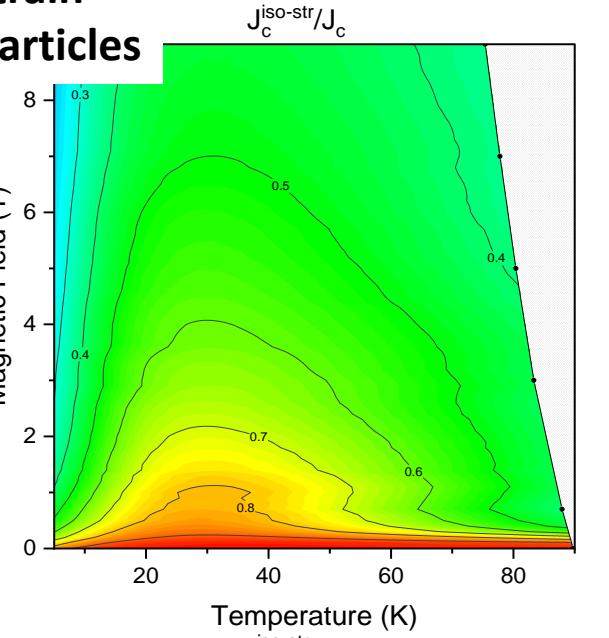
# TLAG Vortex Pinning diagrams

$$J_c(T) = J_c^{iso-wk}(T) + J_c^{iso-str}(T) + J_c^{aniso-str}(T)$$

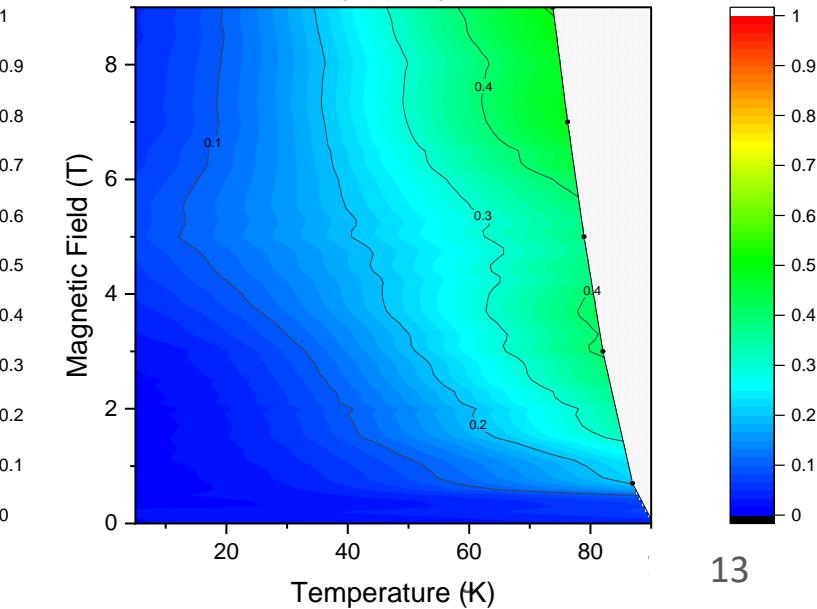
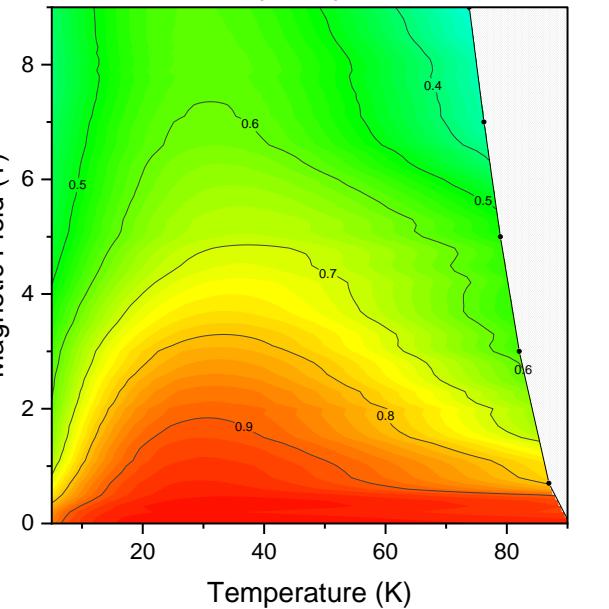
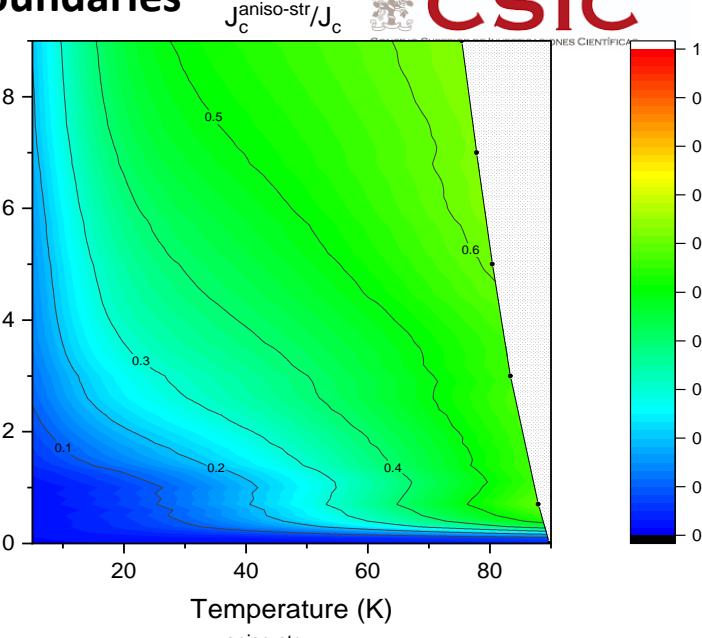
Atomic,  
cluster  
vacancies



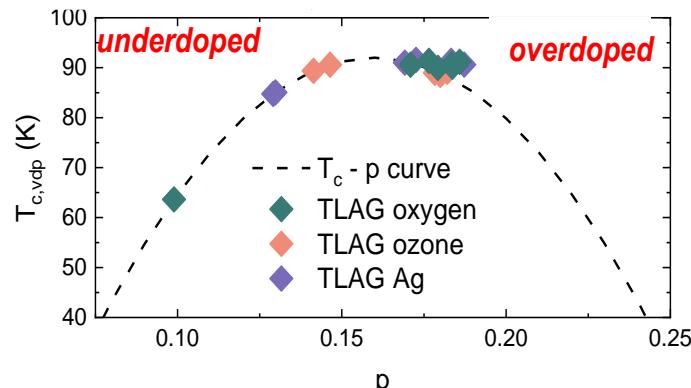
Nanostrain  
Nanoparticles



Twin boundaries



# The overdoped state: Opportunity to increase pinning efficiency



where charge carrier density and condensation energy increases

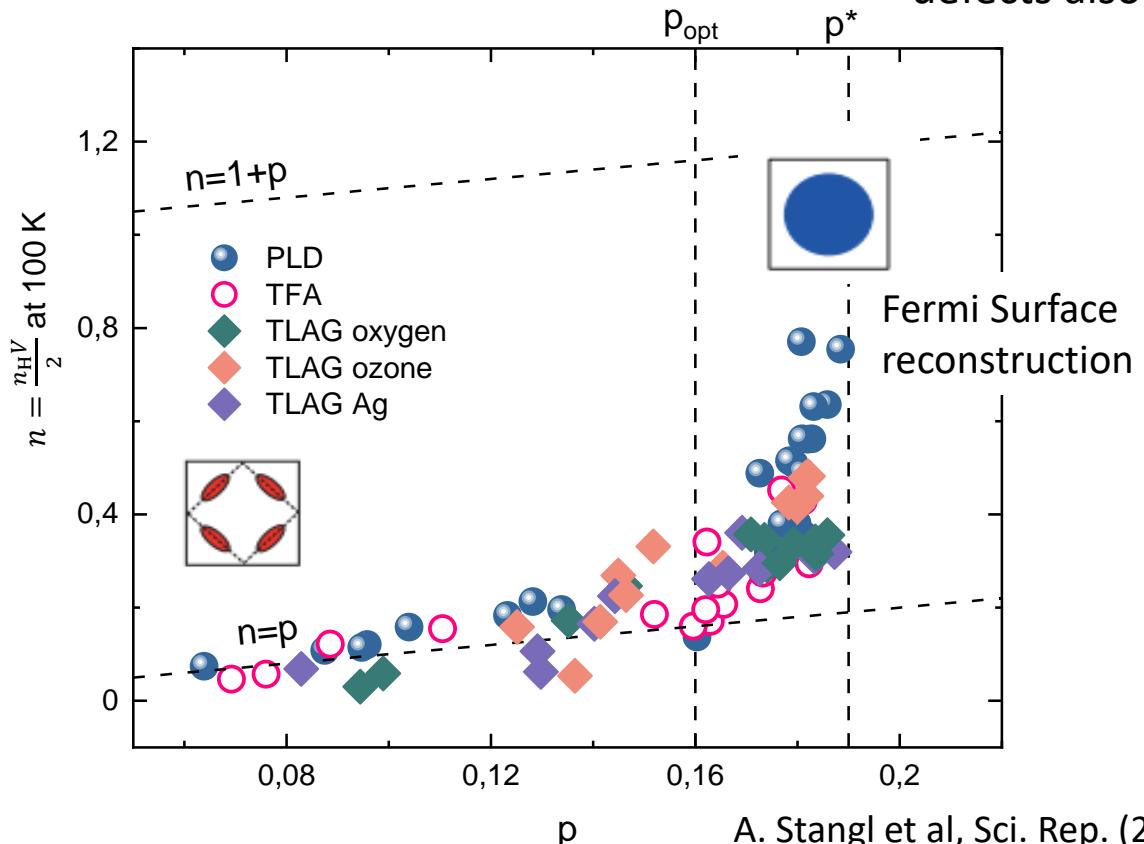
$$n_H \propto E_c \propto f_p$$

Strong increase of  $J_c$  in overdoped state

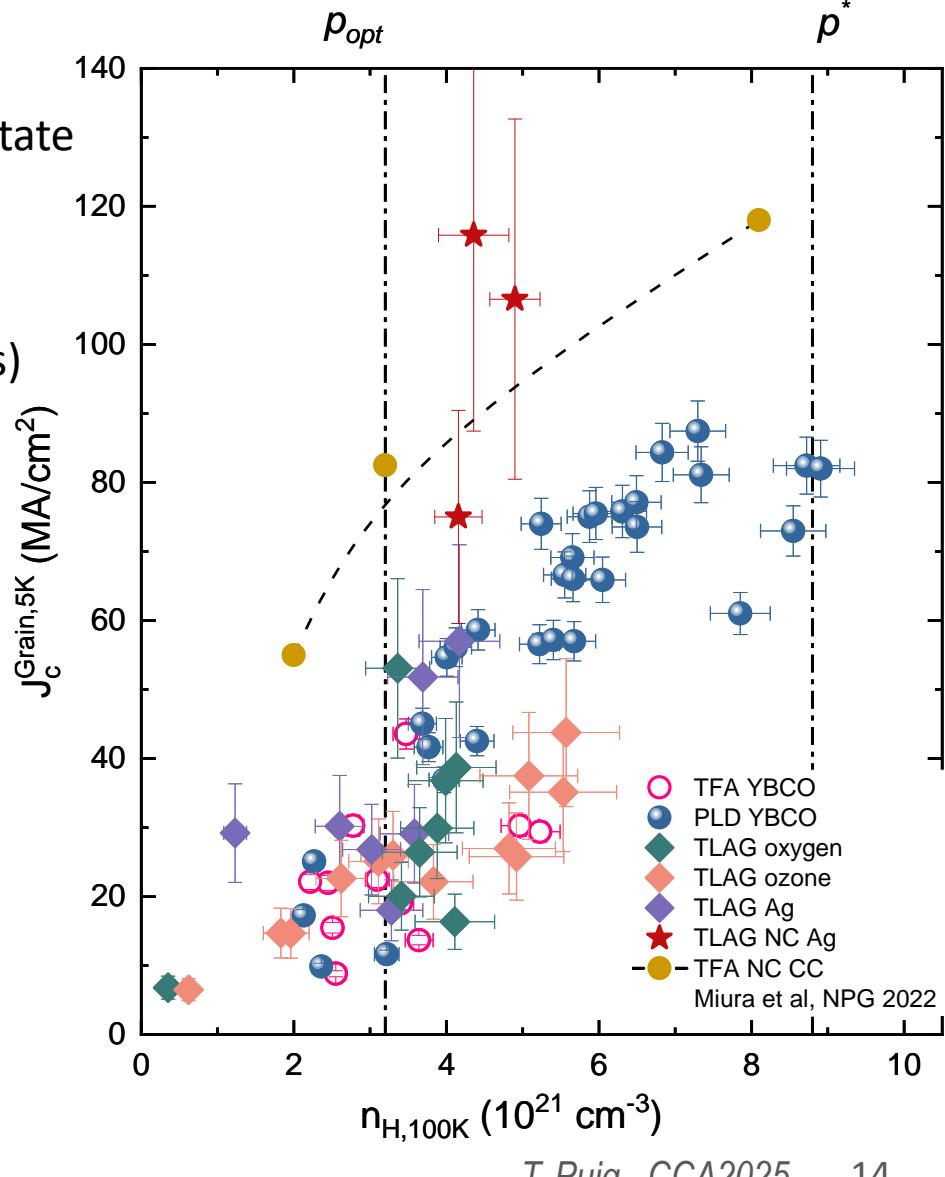
$$\lambda \downarrow, \xi \downarrow \rightarrow E_c \uparrow$$

(Higher efficiency of pinning defects also for nanocomposites)

Study of different oxygenation methods



Fermi Surface reconstruction

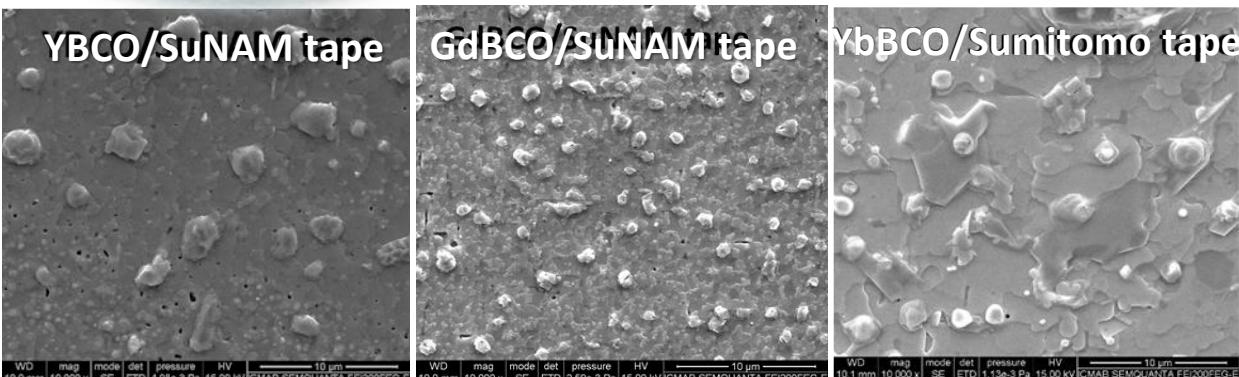
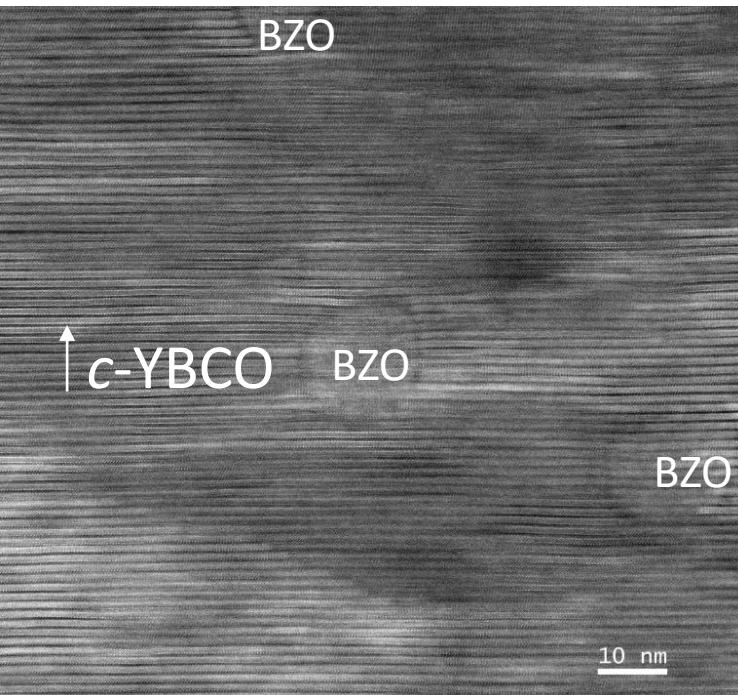
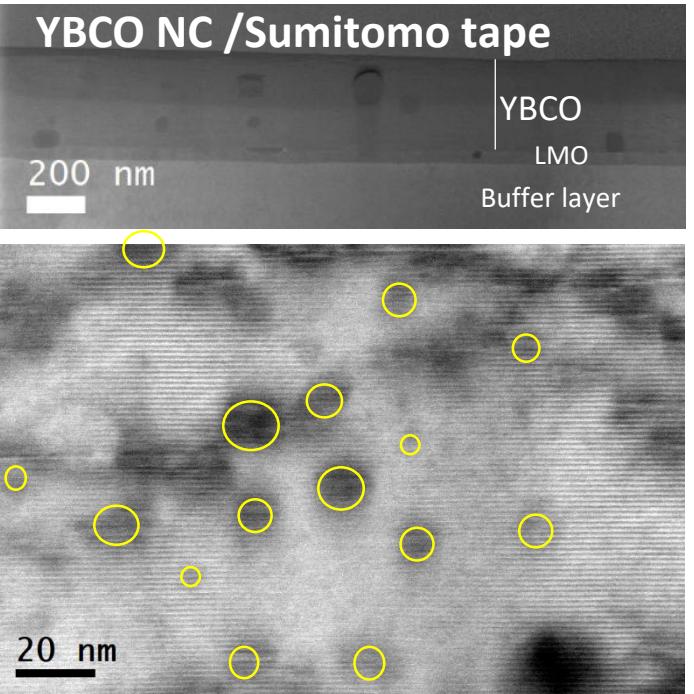


# ⑥ Towards wide area TLAG Coated Conductors



**Colloidal Ink**  
scaled ~ liter

**Slot die**  
now with 40 mm-width  
printhead capabilities



Microstructure is reproduced in 250-750 nm CC  
High superconducting properties:  $J_c(77K) = 1.7-2 \text{ MA/cm}^2$

Construction of a furnace for 40 mm-wide tape is on going

# Conclusions and outlook

- TLAG is a high-throughput process, very versatile and with a large processing window that can support large volume CC fabrication while reducing cost/performance ratio
- In-situ Synchrotron techniques are ideal to underpin the TLAG mechanisms
- High Throughput Experimentation with combinatorial gradients and AI should accelerate the selection of compositions and conditions
- Vortex pinning in the overdoped state is the future to achieve higher efficiency due to the increase in condensation energy in a robust way
- TLAG should be a large area processing method that adapts to the needs of increased production as well as opens to new applications

